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Zero-Cost Specialized Measuring Tool for Wirebond

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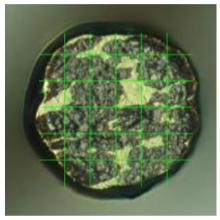
Abstract—This paper presents a specialized measurement grid tool for wirebond intermetallic coverage (IMC), with zero-cost implementation.

Keywords— IMC; intermetallic coverage; wirebond; grid tool.

I. PROJECT OBJECTIVE

- Provide specialized measurement tool for quantifying or measuring wirebond intermetallic coverage (IMC) and other IMC-related anomalies, for New Product Introduction (NPI) and Assembly Process Control
- Zero-cost implementation by utilizing existing software licenses and available resources
 - o Instead of purchasing brand-new measurement equipment or software measurement tool, one great challenge is to come up with an innovative and costeffective solution by maximizing existing/available resources

- II. PROBLEM IDENTIFICATION - WIREBOND IMC WITH VISUAL MEASUREMENT
- Previous methodology utilized manual grids to measure or estimate the magnitude of the IMC



IMC for Gold wire: Accept if $\geq 75\%$ Reject if < 75%

Fig. 1. Example of Gold (Au) wire ball impression.

III. SOLUTION IMPLEMENTATION

